

## LECTURE VIII

# PCB Design Concepts

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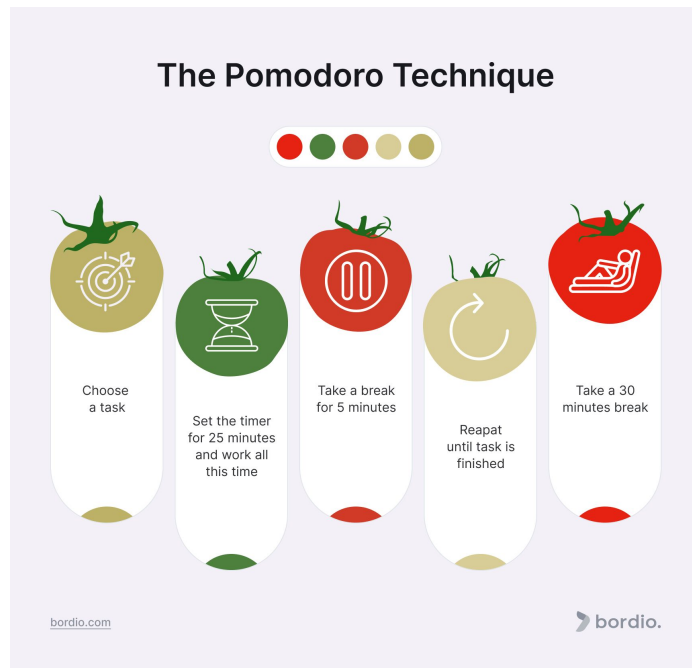
# OPS Instructor Applications!

- OPS Instructor Applications are coming out Wednesday night! The link to apply will be in the discord.
- Being an OPS instructor means:
  - Being able to influence next year's program/curriculum
  - Helping out students new to EECS concepts
  - Being able to join IEEE as an official board member and get to know other cool people!
- Consider applying! Ask any instructor if you have any questions :)
- **OPS Students who have completed their projects have higher priority when applying!**



# Challenge Projects!

- **Reminder: Project X is due March 30!**
  - This is a challenge project, so it is optional (but highly recommended!)
- **A second challenge project is on the way as well!**
  - Pomodoro Timer
  - Will also be due March 30
  - ALSO OPTIONAL!



## SECTION I

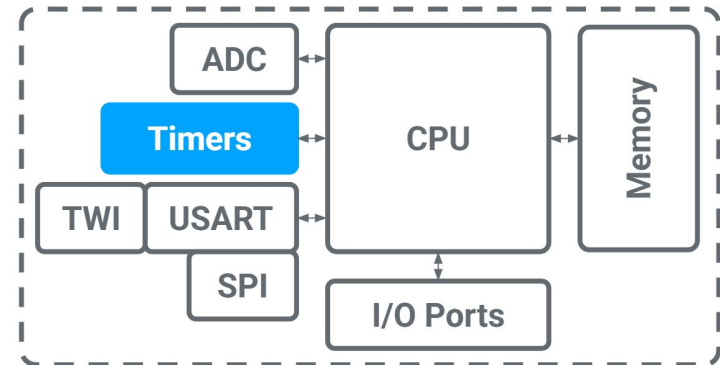
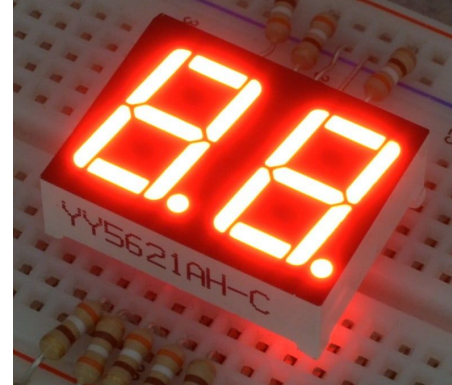
# Project VII Review

# Project 7 Review

- Create a **digital stopwatch** using interrupts, timers, and a 7-segment display
- Due date: 2/23/2026 at 11:59PM

## Learning Concepts:

- Interrupts
- Timers
- Arduino IDE Libraries (Continued)

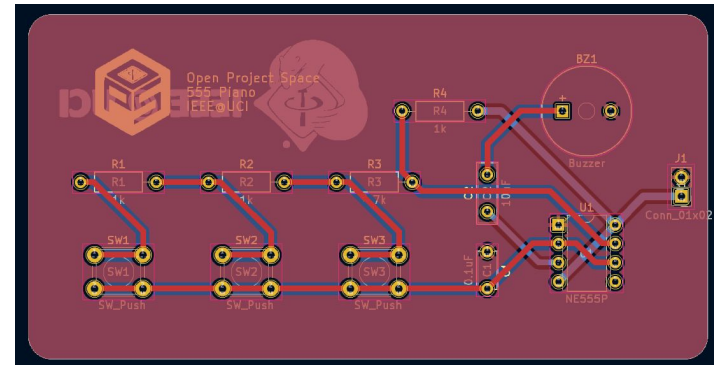
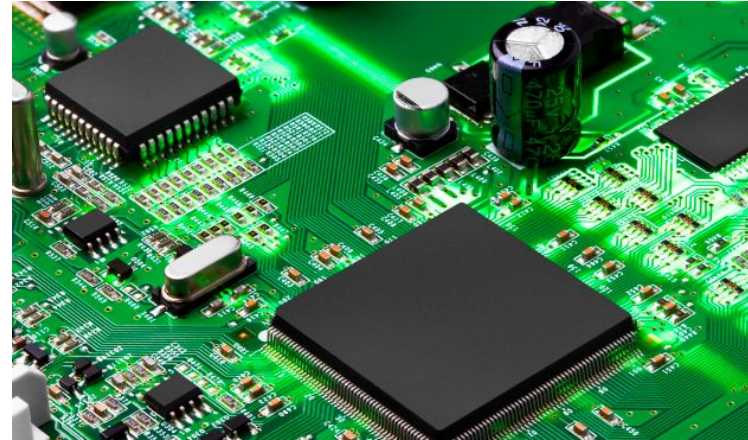


# Project 8

- Design a **PCB** for the 555 Blinking LED or Piano.
- Due date: 3/13/2026 at 11:59PM
- This project is optional!

## Learning Concepts:

- KiCAD
- Schematics
- PCB Design
- PCB Manufacturing



## **SECTION I**

# **Introduction to PCBs**

# Printed Circuit Boards (PCBs)

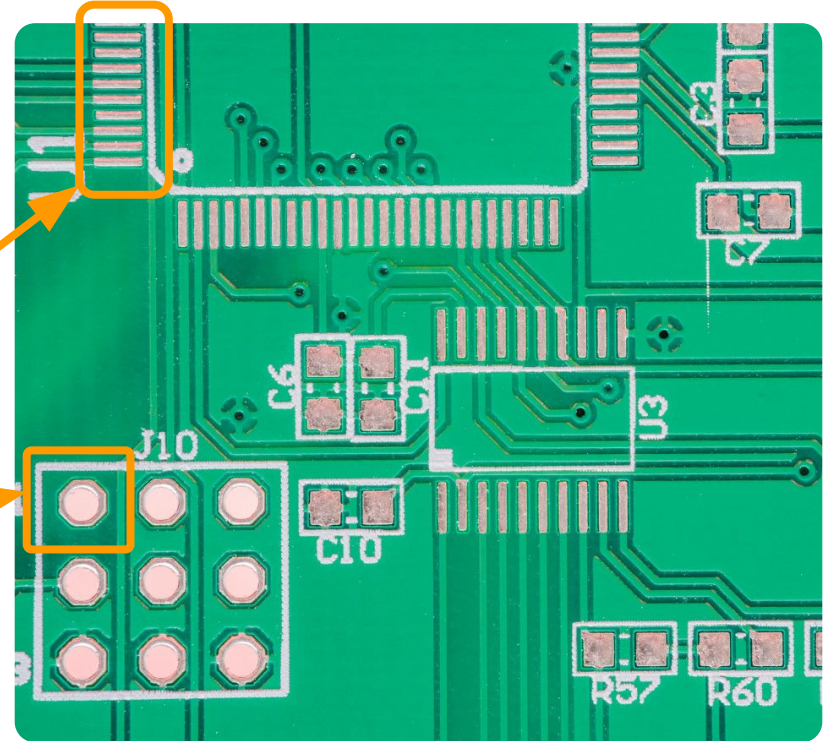
- A **printed circuit board (PCB)** is an electronic assembly that uses copper conductors to **connect components**
  - It acts as a permanent map in placing and connecting electronic components
  - Made from **multiple, alternating layers of conductive** (usually copper) and **insulating material**





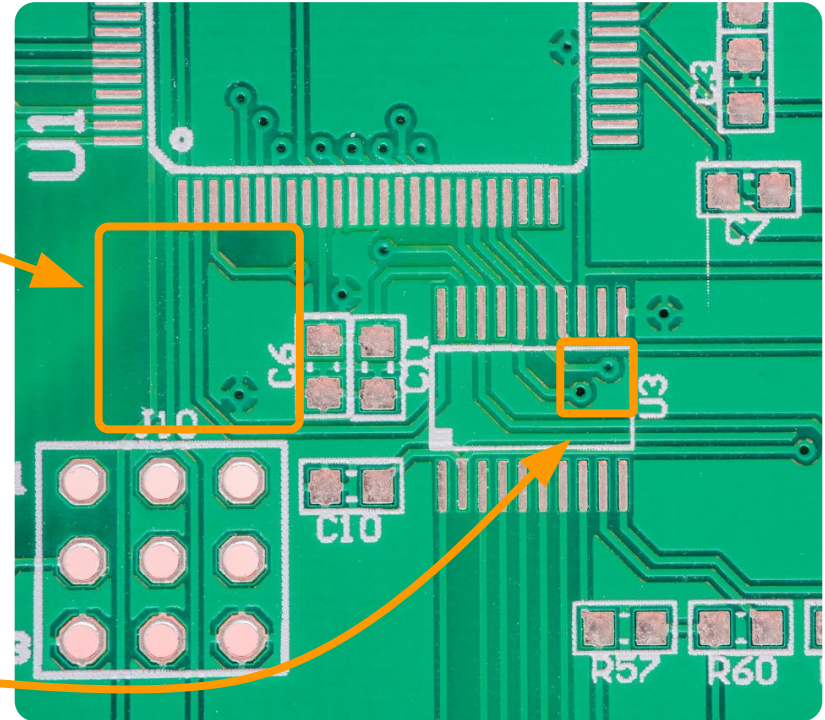
# How are Components Connected?

- **Pads** are exposed copper surfaces which connect the leads of the electronic components to the board
  - Some pads are designed for **surface-mounted (SMD)** leads while others are for **through-hole (THT)** leads
  - Component **leads are soldered to the pads**



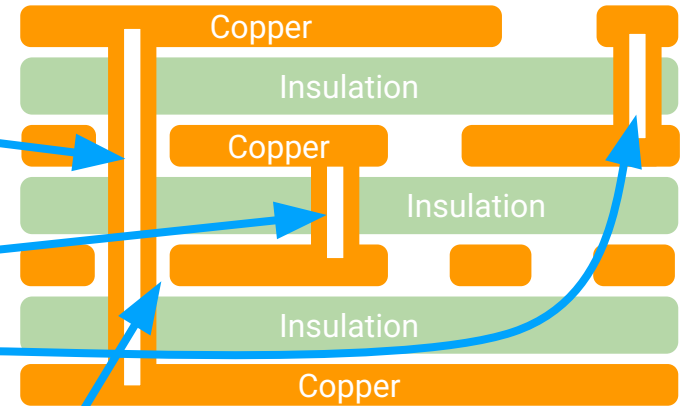
# How are Components Connected? (Cont'd)

- **Traces** are **copper tracks** which connect pads
  - They are covered by a layer called the **solder mask** (colored green in the image)
- **Vias** are **conductive holes** drilled into the board to **connect different copper layers**



# More on Vias

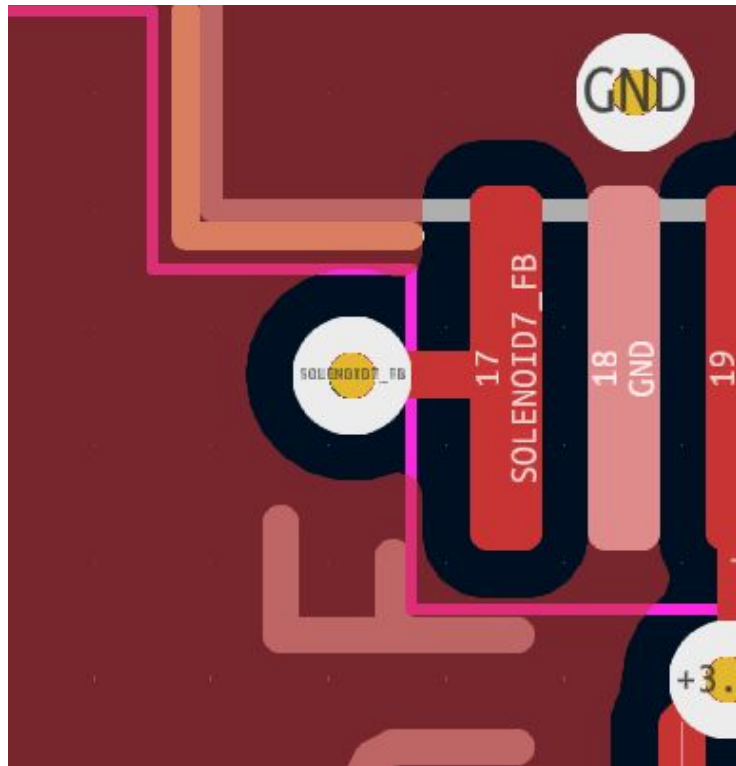
- Common via types...
  - **Through hole via** - drilled and plated from **top layer to bottom layer**
  - **Blind via** - drilled and plated **between two internal layers**
  - **Buried via** - drilled and plated from an **outside layer to an internal layer**
- A **void surrounds the via to prevent a connection** on copper layers which it should not connect
  - Copper layers are not connected from the void



Example PCB Cross Section

# How are Components Connected? (Cont'd)

- A **plane** is an **inner conductive layer**
  - Used to create a ground point
- **Fills** are **large areas of copper** used for the same purpose as planes but can be integrated into the **same layer as traces**
  - The transparent shape surrounding the vias and the pads on the right is a Fill, that is used to ground the ground pad



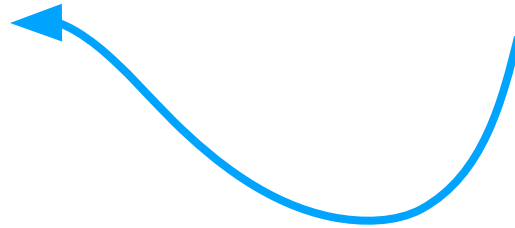
## SECTION II

# PCB Layers

# PCB Stack-Up

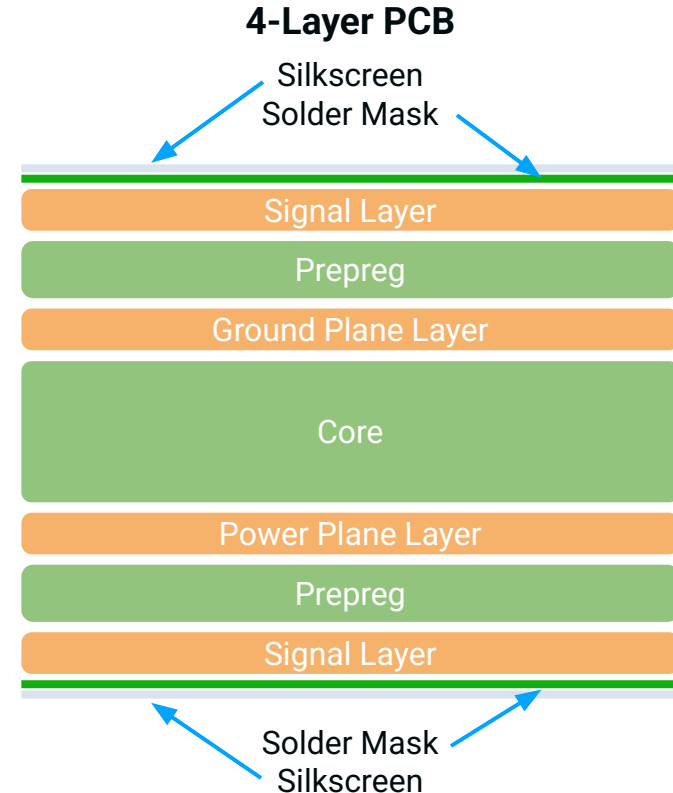
- The **PCB Stack-Up** is the **arrangement** of PCB layers
- Most PCBs have multiple of the following layers:
  - **Copper layer**
    - Signal or routing layer
    - Ground/Power plane layer
  - **Insulation layer**
    - Core
    - Prepreg
  - **Solder mask layer**
  - **Silkscreen layer**

Let's talk about each layer in greater detail



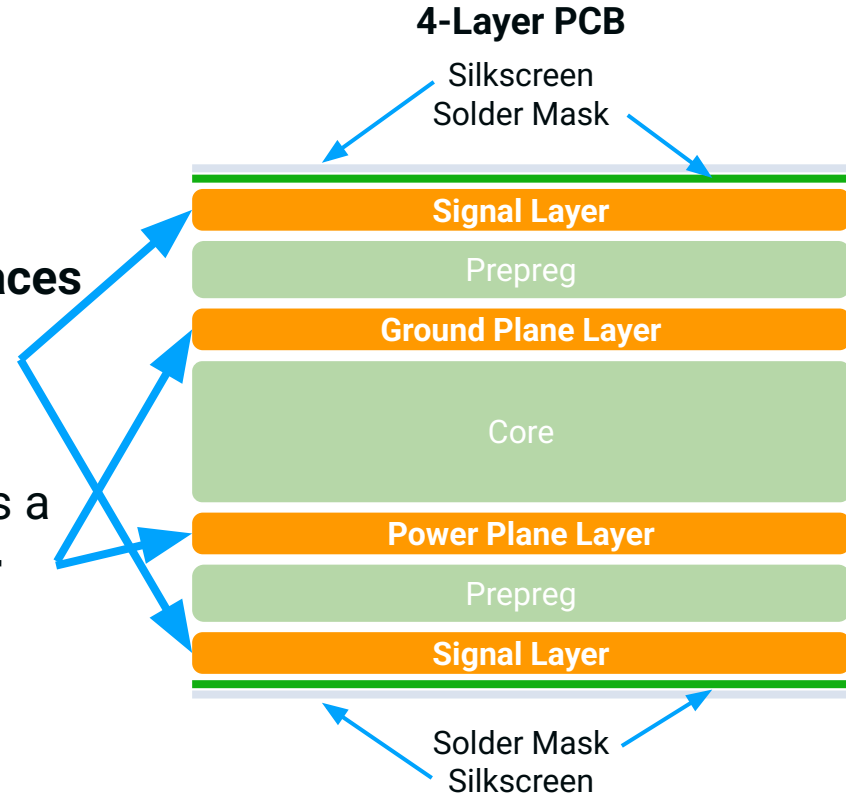
# PCB Stack-Up (Cont'd)

- We will analyze an example stack-up for the **4-layer PCB**
  - An “x-layer PCB” contains x copper layers
- Note the **alternating pattern** of conductive and insulating layers



# Copper Layer

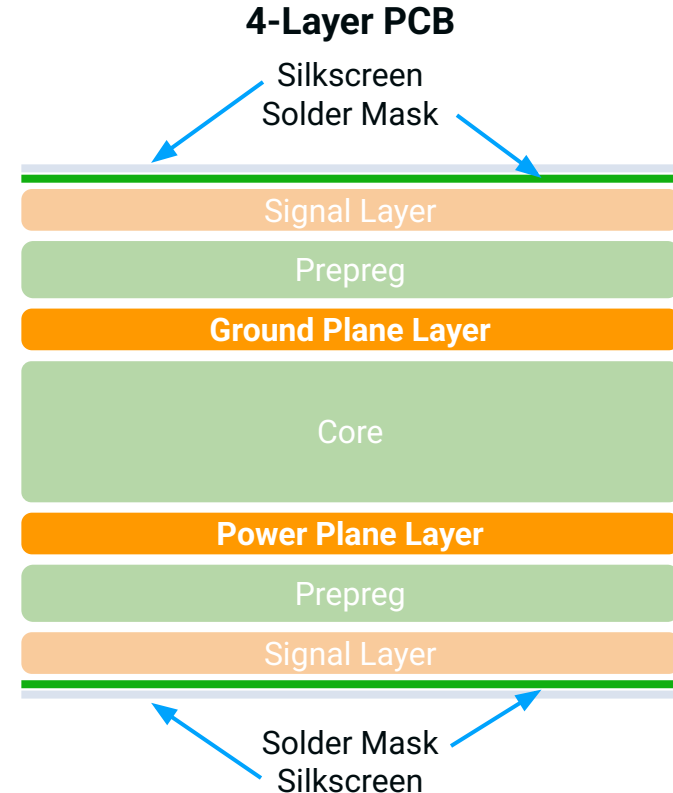
- Each **copper layer** facilitates current flow between circuit components
- There are two types of copper layers:
  - A **signal/routing layer** is where the **traces and pads** are etched for connecting components
  - A **ground/power plane layer** serves as a **path to the common ground or power voltage**





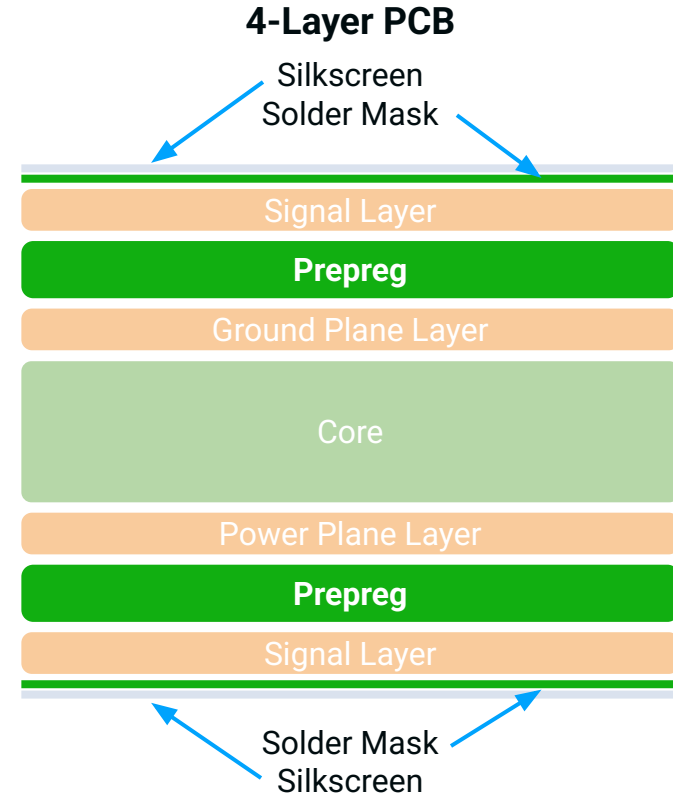
# Copper Layer (Cont'd)

- **Why bother with a ground or power plane layer?**
  - Ground/power planes reduce electromagnetic interference (EMI) and improve the board's heat dissipation
  - A ground plane separating layers of high speed signals can decrease the amount of EMI leaking from one signal to the other



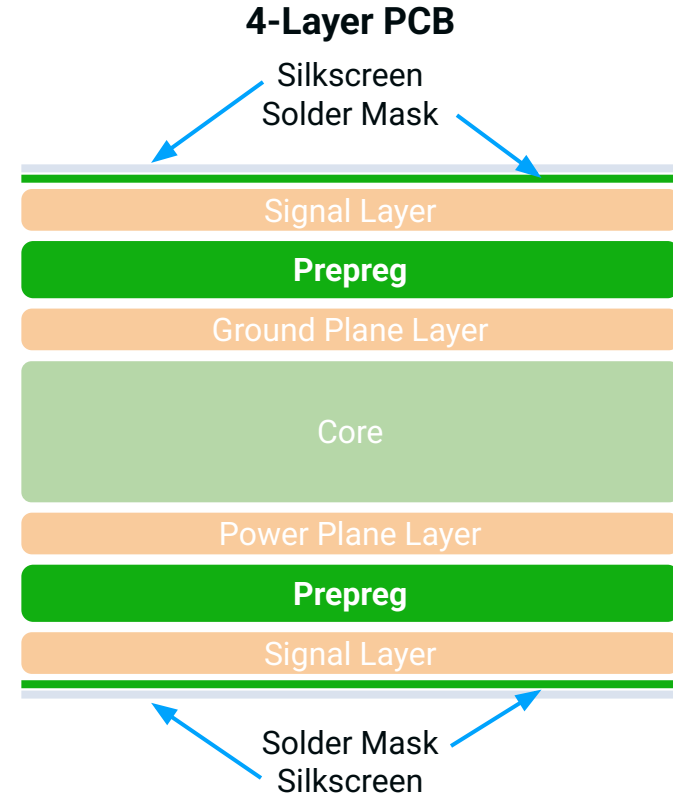
# Prepreg Layer

- **Prepreg** is an **insulator layer** that separates the copper layers and acts as the “glue” to hold the core and copper layers together
  - It is **uncured** and contains resin which is responsible for its “sticky” property
  - When cured with heat and pressure, prepreg bonds all the layers together



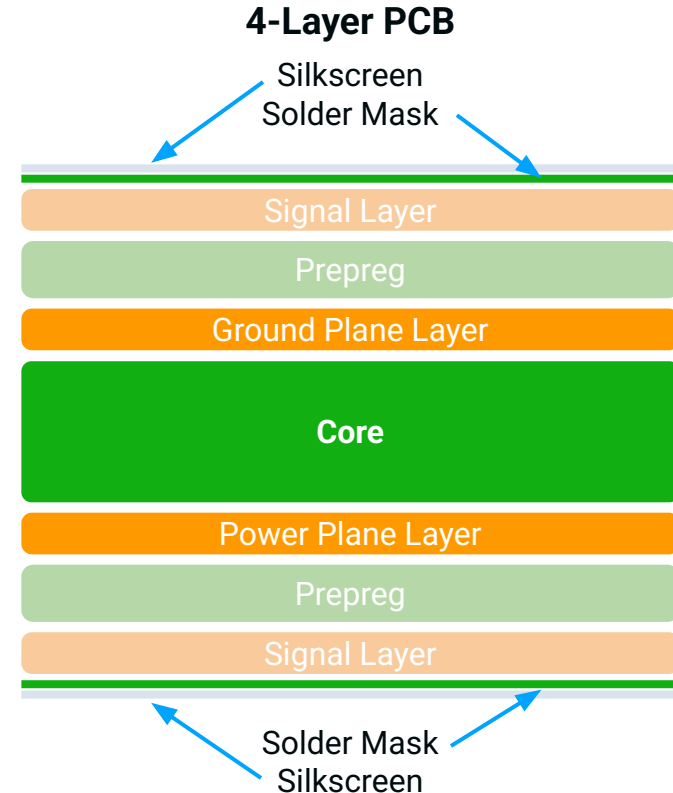
# Prepreg Layer (Cont'd)

- Prepreg is made of **substrate** (insulating material)
  - Common substrates are...
    - **Fiberglass-epoxy** (often FR-4)
      - Most often used
      - Cheap
    - **PTFE (known as Teflon)**
      - Better thermal stability and anti-electrical properties than FR-4 but much more expensive



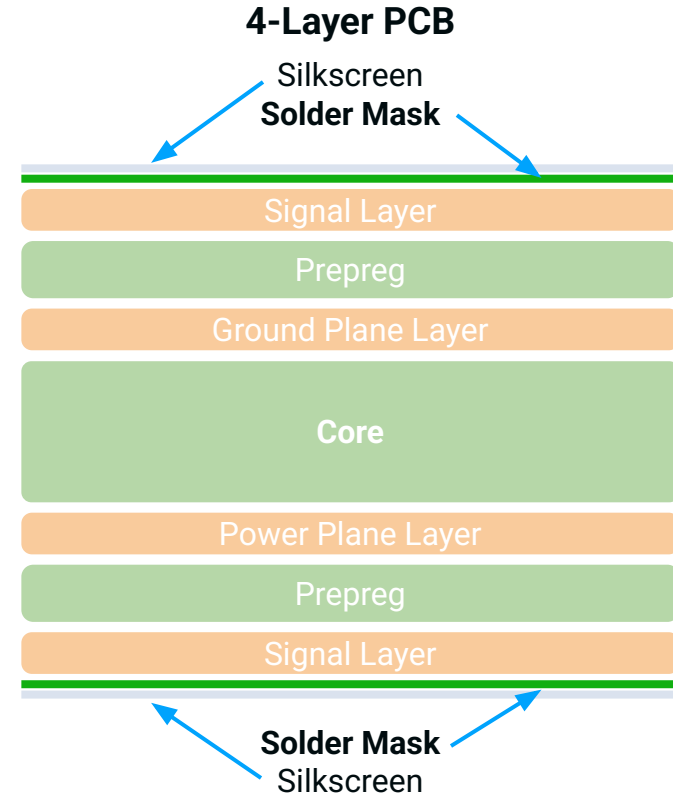
# Core Layer

- **Core** is an **insulator layer** made of multiple prepreg layers pressed together, **plated with copper layers on either side**, and **cured**
  - It technically incorporates the two adjacent copper layers
- In a 2-layer PCB, **usually** only one core exists
- In a 4-layer PCB, **usually** only one core exists, separated by prepreg on either side



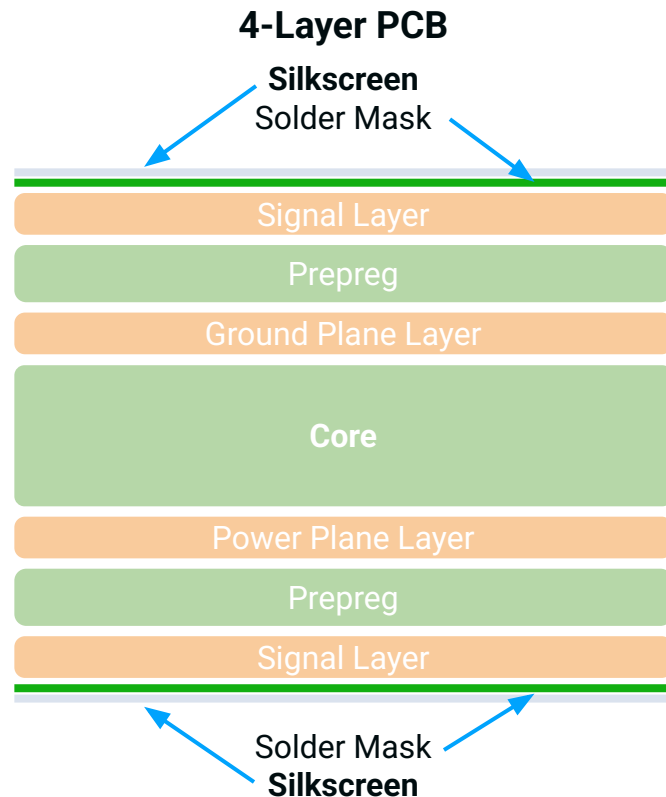
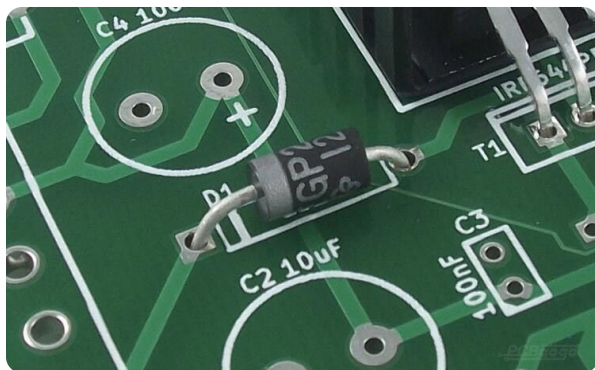
# Solder Mask Layer

- Both outer copper layers are covered by a **solder mask layer**
  - It is a thin resin or filler that is used to **protect outer traces from oxidation** and **prevent solder bridges** between pads
  - It is the green material you see on the surface of the PCB (can be made into a different color :00)



# Silkscreen Layer

- The **silkscreen** is a layer of ink traces (often white) used for symbols, logos, and other component markings
  - It is the outermost layer on either side of the board



## **SECTION III**

# **PCB Fabrication**

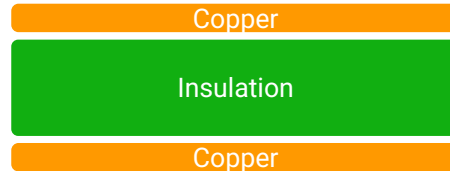
# Fabrication Process Overview

2-Layer PCB

1. **Raw materials are cut** into boards and **holes are drilled**



2. Core, prepreg, and copper **layers are set and cured** (lamination)



3. Copper layers are **etched** to remove excess copper, **leaving only the traces**

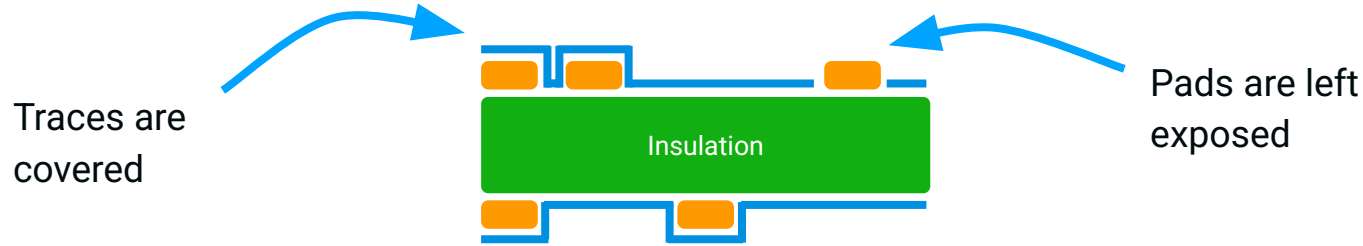




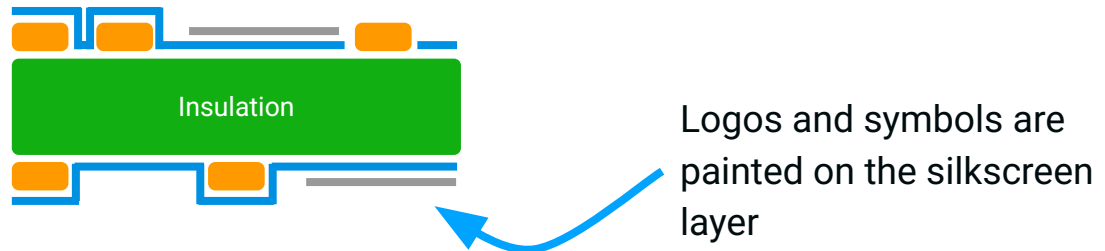
# Fabrication Process Overview (Cont'd)

## 2-Layer PCB

4. The **solder mask is applied** to outer copper layers



5. The **silkscreen is painted** onto the solder mask

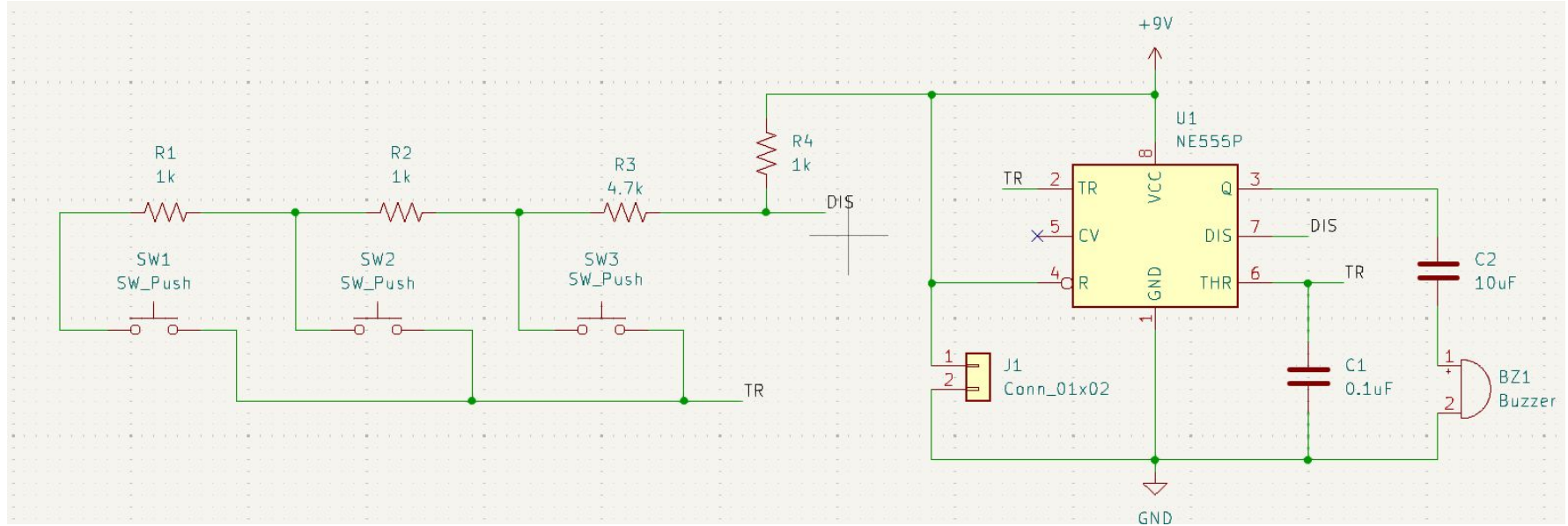


## **SECTION IV**

# **PCB Design Process**



# PCB schematic

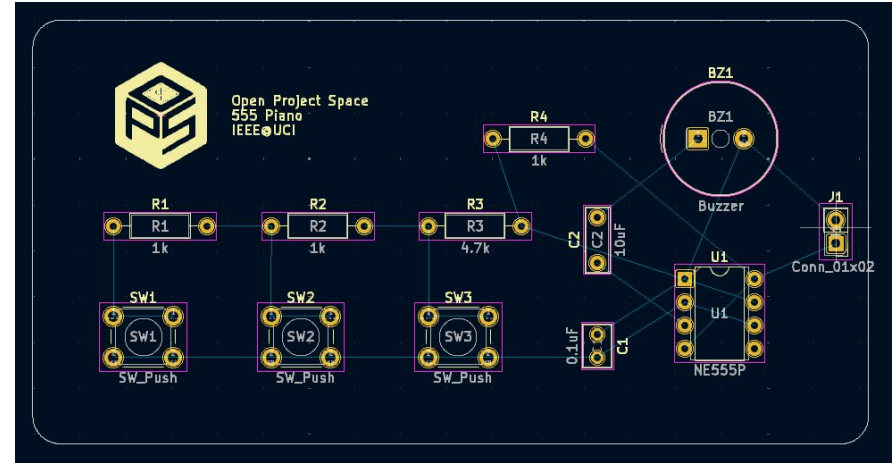


**This look familiar?**

# PCB Design Process (Cont'd)

## 3. Component placement and routing

- Arrange the components on the PCB layout; when placing components, consider (in order of priority)...
- The board shape
- Connector locations
- Heat dissipation requirements

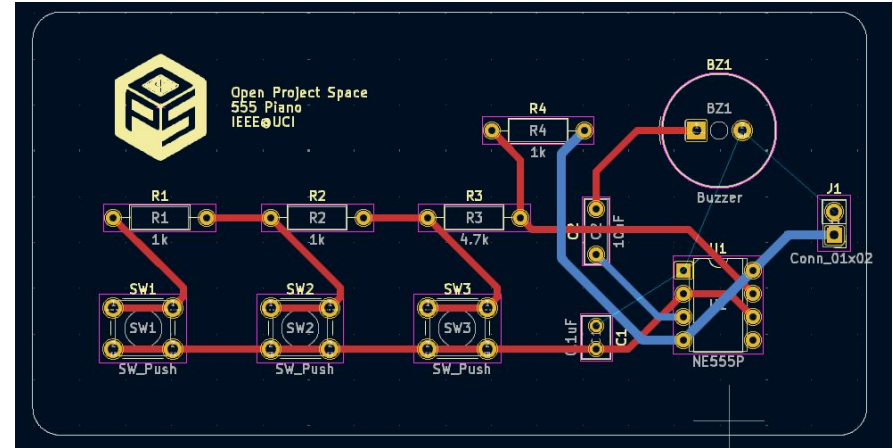


KiCad Component placing

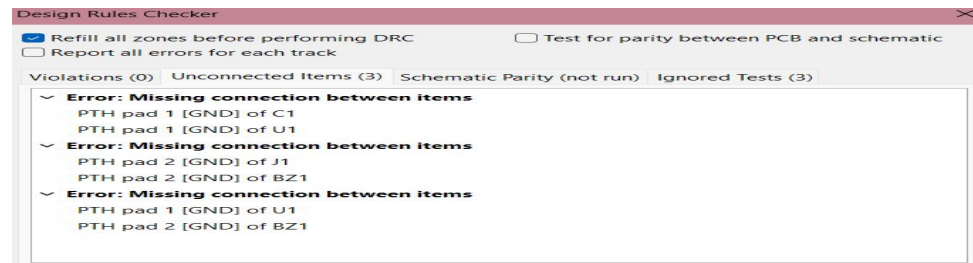
# PCB Design Process (Cont'd)

## 3. Component placement and routing (Cont'd)

- Route the traces between component pads
- EDA tools will make sure the layout conforms to the schematic you defined
- **DESIGN RULES CHECK (DRC)**
  - Checks if there are any tolerance errors or unconnected components

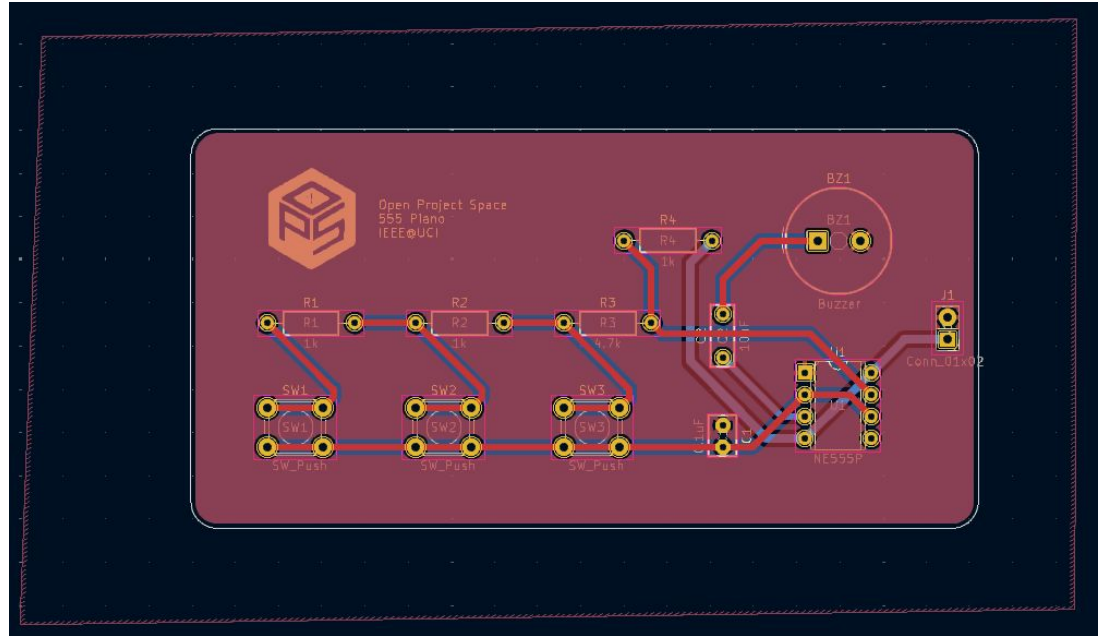


KiCad Routing



# PCB Design Process (Cont'd)

- Fill zones
  - Fills in the rest of the empty pcb with copper
  - Can connect component together
  - We normally used the top and bottom fills with ground



**KiCad Fill zones**

# PCB Design Process (Cont'd)

## 4. **Verification**

- EDA software will have design rules checking tools to make sure components are properly connected and traces correctly routed

## 5. **Generate the manufacturing files**

- EDA software will create the files which you share with a manufacturer
- These files are used by machines for automated PCB fabrication

## 6. **Fabricate the PCB**



# PCB EDA Software

- Popular PCB design software are...
  - [Altium Designer](#) (free for UCI students!)
  - [Autodesk EAGLE](#)
  - [KiCAD EDA](#) (Free)
- We will use KiCAD for this course
  - It is an open source schematic capture and PCB design tool

**Altium**  
Designer

 **EAGLE**

 **KiCad**

# PCB Manufacturers

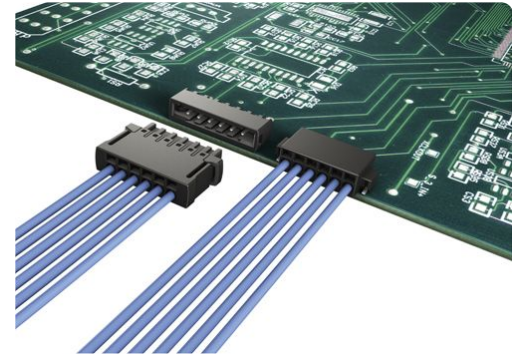
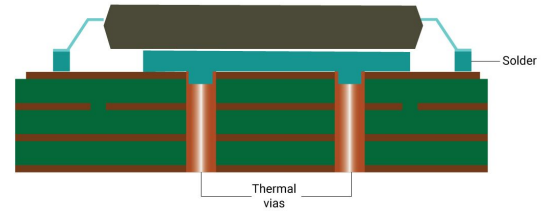
- [JLCPCB](#)
  - Inexpensive 2-layer FR-4 boards
  - Fast manufacturing and shipping
  - Used by hobbyists
- [PCBWay](#)
  - Better for more precise design requirements (small traces, vias, etc.)
  - Advanced manufacturing options

## SECTION V

# PCB Layout Tips

# PCB Layout Tips

- **Use thermal vias to help cool components**
  - **Thermal vias** (unconnected vias) move heat away from components through the board layers
- **Place board-to-wire connectors near the edge of the PCB**
  - It's harder to connect wires in the middle of the PCB



# PCB Layout Tips (Cont'd)

- **Use ground fills or planes** to reduce electrical noise and improve signal integrity
  - **Electrical noise** - random variations in voltage and current, which affects sensitive components
  - **Signal integrity** - how well a signal maintains its original characteristics (strength, shape, timing) from sender to receiver
- **Leave space between pads and traces**
  - Make sure that the pad and trace spacing **adheres to design constraints** (devices packaging, manufacturer requirements)

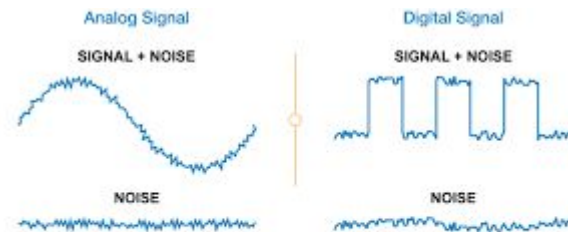
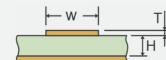


FIGURE 1. Noise in Analog and Digital Signals

## Trace Inductance Calculator

Trace Inductance calculator for wide traces over a ground plane with trace width (W) much larger than substrate thickness (T). Relative Permeability is assumed to be 1. Low frequency, perfect conductor; no skin effect.  
Conditions:  $W \gg H$ ,  $H > T$



$$L \approx \frac{\mu_0 \cdot \mu_r \cdot (H + T/2) \cdot L}{W}$$

Distance units:

Substrate Height, H

Trace Width, W

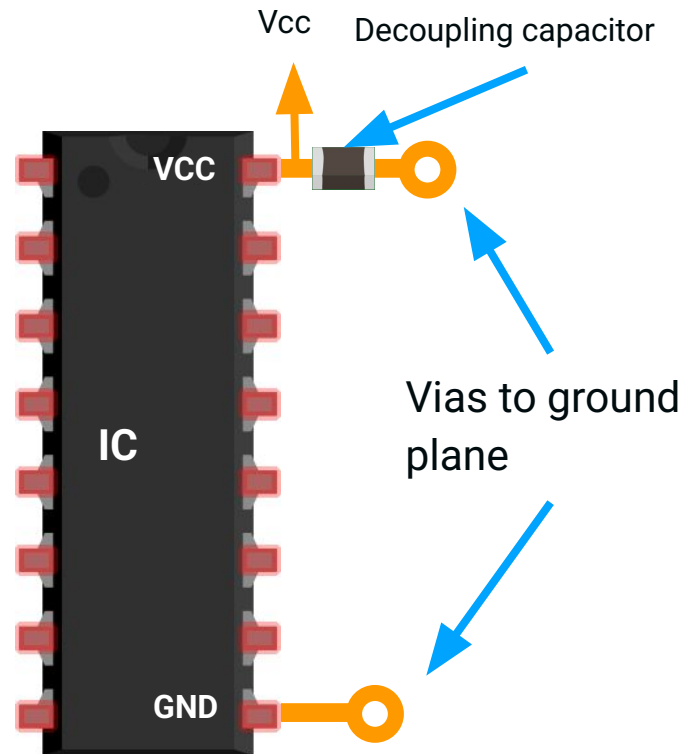
Trace Thickness, T  (1oz=1.4mil)

Trace Length, L

Low frequency inductance  nH

# PCB Layout Tips

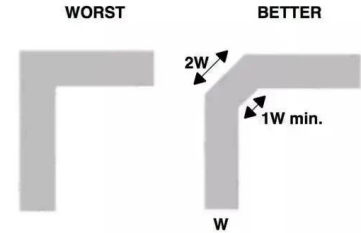
- **Use decoupling capacitors on ICs**
  - **Decoupling capacitors** help **reduce electrical noise** in power supply signals
  - **Ensures a clean and stable power supply** for the IC, preventing unexpected behavior and malfunctions
  - Place the capacitor **between the VCC and GND pins** of the IC



# PCB Layout Tips (Cont'd)

- **Avoid 90° trace angles**

- Use 135° angles instead
- The corners of 90° angles are narrower than the standard trace width; traces should be consistent widths
- 90 degree are harder to etch as a trace



- **Make the power and ground planes big as possible**

- Reduces heat buildup from high current
- Improves signal integrity
- Signal traces, which are low current, may be narrower

# Setting up KiCad

- **Get out your laptops!**
- We will be setting up KiCad
  - This tutorial will be available on the project page when it releases





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